

CLAIMS

1. A method for mounting a flexible substrate during the fabrication of a liquid crystal display (LCD), the method comprising:

- 5 forming a first rigid support substrate with trenches;
 forming a first flexible substrate overlying the first support substrate;
 injecting adhesive into the first rigid support substrate trenches; and
10 curing the adhesive to attach the first flexible substrate to the first support substrate.

2. The method of claim 1 further comprising:
 subsequent to additional LCD fabrication processes,
15 detaching the first support substrate and adhesive from the first flexible substrate.

3. The method of claim 1 further comprising:
 depositing a plurality of patterned integrated circuit films
20 overlying the first flexible substrate, forming thin film transistors (TFTs);
 forming a liquid crystal (LC) layer overlying the TFTs;
 and,
 forming a color filter layer over the LC layer.

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4. The method of claim 3 further comprising:

forming a second flexible substrate overlying the color filter;

forming a second rigid support substrate with trenches overlying the second flexible substrate;

5 injecting adhesive into the second rigid support substrate
trenches; and

curing the adhesive to attach the second flexible substrate to the second support substrate.

10 5. The method of claim 1 wherein injecting adhesive
into the first rigid support substrate trenches includes injecting the
adhesive in a vacuum environment.

6. The method of claim 5 wherein forming a first rigid
15 support substrate with trenches includes forming trenches with at
least one trench mouth;

wherein injecting adhesive into the first support substrate trenches includes:

creating a vacuum environment in the first rigid support
20 substrate trenches;

supplying adhesive to the at least one mouth of the first rigid support substrate trenches;

in response to returning the first rigid support substrate to ambient pressure, pulling the adhesive into the first rigid support substrate trenches vacuum environment through the at least one mouth.

7. The method of claim 6 wherein returning the first rigid support substrate to ambient pressure includes supplying an N₂ atmosphere at ambient pressure.

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8. The method of claim 1 wherein forming the first rigid support substrate with trenches includes forming a rigid support substrate from a material selected from the group including glass and plastic.

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9. The method of claim 1 wherein forming the first flexible substrate overlying the first rigid support substrate includes forming a flexible substrate from a material selected from the group including plastic and metal films.

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10. The method of claim 1 wherein forming the first rigid support substrate with trenches includes:

forming a rigid support substrate with a top surface;

forming a photoresist pattern with openings exposing the

20 underlying support substrate top surface;

etching the exposed support substrate top surface to form the trenches in the support substrate; and

removing the photoresist.

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11. A method for mounting a flexible substrate in the fabrication of a liquid crystal display (LCD), the method comprising:

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forming a first rigid support substrate;
distributing a first pattern of spacers, with spacer
channels between the spacers, overlying the first support substrate;
forming a first flexible substrate overlying the first pattern
5 of spacers;
injecting adhesive into the spacer channels; and
curing the adhesive to attach the first flexible substrate to
the first support substrate.

10 12. The method of claim 11 further comprising:
subsequent to additional LCD fabrication processes,
detaching the first support substrate, spacers, and adhesive from the
first flexible substrate.

15 13. The method of claim 11 further comprising:
depositing a plurality of patterned integrated circuit films
overlying the first flexible substrate, forming thin film transistors
(TFTs);

forming a liquid crystal (LC) layer overlying the TFTs;
20 and,
forming a color filter layer over the LC layer.

14. The method of claim 13 further comprising:
forming a second flexible substrate overlying the color
25 filter;

distributing a second pattern of spacers, with spacer channels between the spacers, overlying the second flexible substrate; forming a second rigid support substrate overlying the second pattern of spacers;

5 injecting adhesive into the spacer channels; and curing the adhesive to attach the second flexible substrate to the second support substrate.

15. The method of claim 11 wherein injecting adhesive

10 into the spacer channels includes injecting the adhesive in a vacuum environment.

16. The method of claim 15 wherein distributing a pattern of spacers, with spacer channels between the spacers

15 includes forming spacer channels with at least one mouth; and wherein injecting adhesive into spacer channels includes: creating a vacuum environment in the spacer channels; supplying adhesive to the at least one spacer channel mouth;

20 returning the first rigid support substrate to ambient pressure; and in response to returning the first rigid support substrate to ambient pressure, pulling the adhesive into the spacer channels vacuum environment through the at least one mouth.

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10 19. The method of claim 11 wherein forming the first flexible substrate overlying the pattern of spacers includes forming the first flexible substrate from a material selected from the group including plastic and metal films.

21. The structure of claim 20 further comprising:
25 integrated circuit (IC) films, formed into thin film
transistors (TFTs), overlying the first flexible substrate.

22. The structure of claim 21 further comprising:
a liquid crystal (LC) layer overlying the TFTs;
a color filter overlying the LC layer.

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23. The structure of claim 22 further comprising:
a second flexible substrate overlying the color filter;
a second rigid temporary support substrate with trenches
overlying the second flexible substrate; and,

10 vacuum injected adhesive in the second temporary
support substrate trenches to attach the second temporary rigid
support structure to the second flexible support structure.

24. The structure of claim 20 wherein the first
15 temporary support substrate is made from a material selected from
the group including glass and plastic.

25. The structure of claim 20 wherein the first flexible
substrate is made from a material selected from the group including
20 plastic and metal films.

26. A structure to support a flexible substrate liquid
crystal display (LCD) during fabrication, the structure comprising:
a first rigid temporary support substrate;
25 a first temporary pattern of spacers, with spacer channels
between the spacers, overlying the first temporary support substrate;

a first flexible substrate overlying the first temporary pattern of spacers; and

vacuum injected adhesive in the spacer channels to attach the first temporary support substrate to the first flexible
5 substrate.

27. The structure of claim 26 further comprising:
integrated circuit (IC) films, formed into thin film transistors (TFTs), overlying the first flexible substrate.

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28. The structure of claim 27 further comprising:
a liquid crystal (LC) layer overlying the TFTs; and,
a color filter overlying the LC layer.

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29. The method of claim 28 further comprising:
a second flexible substrate overlying the color filter;
a second temporary pattern of spacers, with spacer channels between the spacers, overlying the second flexible substrate;
a second rigid temporary support substrate overlying the
20 second temporary pattern of spacers; and,

vacuum injected adhesive in the spacer channels to attach the second temporary support substrate to the second flexible substrate.

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30. The structure of claim 26 wherein the first temporary support substrate is made from a material selected from the group including glass and plastic.

5 31. The structure of claim 26 wherein the first flexible substrate is made from a material selected from the group including plastic and metal films.

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